

IPW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Hideyo Osanai et al. Confirmation No.:
Serial No. : 10/747,837
Filed : December 29, 2003
TC/A.U. :
Examiner :

Docket No. : 03-745
Customer No. : 34704

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

In accordance with the requirements of 37 CFR 1.97 and 1.98, Applicants hereby submit the documents listed hereinbelow, which were cited in the European Search report, copies enclosed.

- (1) Patent Abstracts of Japan Publication No. 11000728
entitled HEAT SINK AND METHOD FOR..., By Terada Atsushi,
published January 6, 1999. The abstract is attached
hereto.
- (2) U.S. Patent No. 4,788,765 entitled METHOD OF MAKING
CIRCUIT ASSEMBLY WITH..., By Kaufman et al., patented
December 6, 1988. The abstract is attached hereto.
- (3) U.S. Patent Application Publication No. 2002/0125563
entitled POWER SEMICONDUCTOR MODULE OF..., By
Scheuermann, published September 12, 2002. The

abstract is attached hereto.

- (4) EP Patent No. 0 523 981 entitled METHOD OF MAKING ELECTRONIC PACKAGES AND..., By Prinz et al., published January 20, 1993. The abstract is attached hereto.
- (5) EP Patent No. 1 187 198 entitled METAL-CERAMIC CIRCUIT BOARD AND..., By Hideyo Osanai, published March 13, 2002. The abstract is attached hereto.
- (6) U.S. Patent No. 3,199,000 entitled MOUNT FOR SEMICONDUCTOR, By P. W. Nippert, patented August 3, 1965. The abstract is attached hereto.
- (7) U.S. Patent No. 5,526,867 entitled METHODS OF FORMING ELECTRONIC PACKAGES, By Keck et al., patented June 18, 1996. The abstract is attached hereto.

The undersigned submits the above-identified references for independent consideration by the Examiner and does not make any admission that these references are or are not material to the

present invention or that these references are or are not prior art with respect to the present invention.

Respectfully submitted,

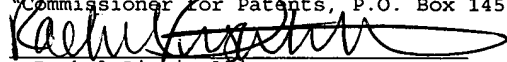
Hideyo Osanai et al.

By 

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Date: May 10, 2004

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313" on May 10, 2004.


Rachel Piscitelli



Approved for use through 07/31/2006. OMB 0651-0031

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Complete if Known

Application Number	10/747,837
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Filing Date	December 29, 2003
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First Named Inventor	Hideyo Osanai et al.
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Art Unit

Examiner Name

Attorney Docket Number	03-745
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U. S. PATENT DOCUMENTS

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